

PCN Number:	20190805000	PCN Date:	Aug. 6, 2019
Title:	Datasheet for LMK04616		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Nov. 6, 2019		
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing a change.
The product datasheet(s) is being updated as summarized below.



LMK04616

SNAS663B – MARCH 2017 – REVISED JULY 2019

Changes from Revision A (May 2017) to Revision B

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• Removed bulleted list under the <i>Dual Loop PLL Architecture</i> feature bullet.....	1
• Added <i>Ultra Low Noise</i> feature bullets	1
• Changed VCO frequency units from: 5.8 to 6.175 GHz to: 5870 MHz to 6175 MHz.....	1
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• Added PACKAGE column to device configuration information table	5
• Added Footnote and link to LMK04610 datasheet	5
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• Changed PLL1 phase detector maximum frequency from 40 MHz to 4 MHz	12
• Changed VCO tuning range minimum from: 5800 to: 5870	12
• Changed V _{OD} symbol to V _{OD,pp} to match mVpp units.	13
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The datasheet number will be changing.

Device Family	Change From:	Change To:
LMK04616	SNAS663A	SNAS663B

<http://www.ti.com/product/LMK04616>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Electrical specification performance changes as indicated above.

Changes to product identification resulting from this PCN:

None.

Product Affected:

LMK04616ZCRR	LMK04616ZCRT		
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